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# BLF0910H6L500; BLF0910H6LS500

**Power LDMOS transistor** 

**AMPLEON** 

Rev. 2 — 13 April 2016

**Product data sheet** 

### 1. Product profile

### 1.1 General description

A 500 W LDMOS power transistor for industrial applications at frequency of 915 MHz.

The BLF0910H6L500 and BLF0910H6LS500 are designed for high-power CW applications and are assembled in high performance ceramic packages.

Table 1. Typical performance

RF performance at  $V_{DS}$  = 50 V;  $I_{Dq}$  = 90 mA in a class-AB application circuit.

Test signal	f	V <sub>DS</sub>	$P_L$	Gp	ησ
	(MHz)	(V)	(W)	(dB)	(%)
CW [1]	915	50	500	18	61
CW pulsed [2][3]	915	50	500	19.5	62.5

- [1]  $T_{case} = 65 \, ^{\circ}C$ .
- [2]  $T_{case} = 25 \, ^{\circ}C$ .
- [3]  $t_p = 100 \ \mu s; \ \delta = 10 \ \%.$

#### 1.2 Features and benefits

- High efficiency
- Easy power control
- Excellent ruggedness
- Integrated ESD protection
- Designed for broadband operation (900 MHz to 930 MHz)
- Internally input matched
- Compliant to Directive 2002/95/EC, regarding Restriction of Hazardous Substances (RoHS)

### 1.3 Applications

Industrial applications in the 915 MHz ISM band

### 2. Pinning information

Table 2. Pinning

Pin	Description		Simplified outline	Graphic symbol
BLF0910	H6L500 (SOT502A)			
1	drain			_
2	gate		\frac{1}{5\frac{1}{1}}_3	
3	source	[1]	2	2 — 3 sym112
BLF0910	H6LS500 (SOT502B)			
1	drain			
2	gate		1 1 3	1 
3	source	<u>[1]</u>	2	2 — 3 sym112

<sup>[1]</sup> Connected to flange.

### 3. Ordering information

Table 3. Ordering information

Type number	Packag	ge		
	Name	Name Description		
BLF0910H6L500	-	flanged ceramic package; 2 mounting holes; 2 leads	SOT502A	
BLF0910H6LS500	-	earless flanged ceramic package; 2 leads	SOT502B	

# 4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Min	Max	Unit
$V_{DS}$	drain-source voltage	-	114.5	V
$V_{GS}$	gate-source voltage	-6	+11	V
T <sub>stg</sub>	storage temperature	<del>-</del> 65	+150	°C
Tj	junction temperature [1]	-	225	°C

<sup>[1]</sup> Continuous use at maximum temperature will affect the reliability, for details refer to the online MTF calculator.

### 5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Тур	Unit
R <sub>th(j-case)</sub>	thermal resistance from junction to case	T <sub>case</sub> = 80 °C; P <sub>L</sub> = 500 W	0.2	K/W

BLF0910H6L500\_H6LS500

### 6. Characteristics

#### Table 6. DC characteristics

 $T_i$  = 25 °C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>(BR)DSS</sub>	drain-source breakdown voltage	$V_{GS} = 0 \text{ V}; I_D = 4 \text{ mA}$	114.5	-	-	V
V <sub>GS(th)</sub>	gate-source threshold voltage	V <sub>DS</sub> = 10 V; I <sub>D</sub> = 400 mA	1.25	1.9	2.35	V
I <sub>DSS</sub>	drain leakage current	V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 50 V	-	-	2.8	μΑ
I <sub>DSX</sub>	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75 \text{ V};$ $V_{DS} = 10 \text{ V}$	-	60	-	Α
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = 11 V; V <sub>DS</sub> = 0 V	-	-	280	nA
g <sub>fs</sub>	forward transconductance	V <sub>DS</sub> = 10 V; I <sub>D</sub> = 20 A	-	29	-	S
R <sub>DS(on)</sub>	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75 \text{ V};$ $I_D = 14 \text{ A}$	-	0.078	-	Ω

#### Table 7. RF characteristics

Test signal: pulsed RF;  $t_p$  = 100  $\mu$ s;  $\delta$  = 10 %; f = 915 MHz; RF performance at  $V_{DS}$  = 50 V;  $I_{Da}$  = 90 mA;  $T_{case}$  = 25  $^{\circ}$ C; unless otherwise specified; in a class-AB production test circuit.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Gp	power gain	P <sub>L</sub> = 500 W	15	19	-	dB
RLin	input return loss	P <sub>L</sub> = 500 W	-	-18	-7	dB
$\eta_{D}$	drain efficiency	P <sub>L</sub> = 500 W	59	63.5	-	%

### 7. Test information

### 7.1 Ruggedness in class-AB operation

The BLF0910H6L500 and BLF0910H6LS500 are capable of withstanding a load mismatch corresponding to VSWR = 30:1 through all phases under the following conditions:  $V_{DS} = 50 \text{ V}$ ;  $I_{Dq} = 90 \text{ mA}$ ;  $P_L = 500 \text{ W}$  (CW); f = 915 MHz.

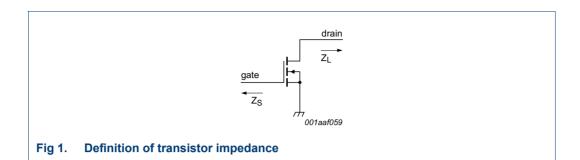
### 7.2 Impedance information

#### Table 8. Typical impedance

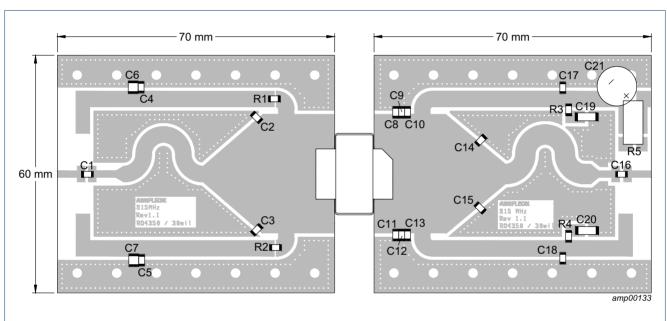
Measured load-pull  $Z_S$  and  $Z_L$  device impedances;  $I_{Dq}$  = 90 mA;  $V_{DS}$  = 50 V; typical values unless otherwise specified.

f	Z <sub>S</sub> [1]	Z <sub>L</sub> [1]
(MHz)	<b>(</b> Ω <b>)</b>	<b>(</b> Ω <b>)</b>
915	1.8 – 1.4j	0.6 + 0.35j

[1] Z<sub>S</sub> and Z<sub>L</sub> defined in Figure 1.



#### 7.3 Test circuit



Printed-Circuit Board (PCB): Rogers RO4350;  $\epsilon_r$  = 3.48; height = 0.762 mm; thickness copper plating = 35  $\mu$ m. See <u>Table 9</u> for a list of components.

Fig 2. Component layout for application circuit

Table 9. List of components

See Figure 2 for component layout.

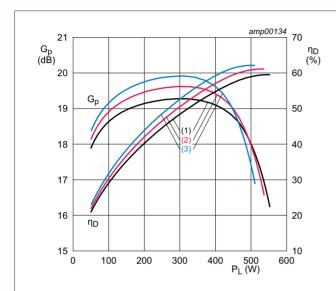
Component	Description	Value	Remarks
C1, C16	multilayer ceramic chip capacitor	470 pF	ATC 800B
C2, C3	multilayer ceramic chip capacitor	2.4 pF	ATC 800B
C4, C5, C17, C18	multilayer ceramic chip capacitor	100 pF	ATC 800B
C6, C7	multilayer ceramic chip capacitor	4.7 μF, 50 V	Murata: GRM32ER71H475KA88L
C8, C11	multilayer ceramic chip capacitor	5.6 pF	ATC 800B
C9, C10, C12, C13	multilayer ceramic chip capacitor	4.7 pF	ATC 800B
C14, C15	multilayer ceramic chip capacitor	0.9 pF	ATC 800B
C19, C20	multilayer ceramic chip capacitor	4.7 μF, 100 V	TDK: C5750X7R2A475KT/A
C21	electrolytic capacitor	470 μF, 63 V	

Table 9. List of components ...continued

See Figure 2 for component layout.

Component	Description	Value	Remarks
R1, R2	resistor	10 Ω	SMD1206
R3, R4	resistor	3 Ω	SMD1206
R5	shunt resistor	0.01 Ω	Ohmite: FC4L110R010FER

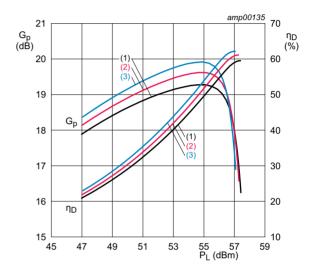
### 7.4 Graphical data



 $V_{DS} = 50 \text{ V}; I_{Dq} = 90 \text{ mA}.$ 

- (1) f = 902 MHz
- (2) f = 915 MHz
- (3) f = 928 MHz

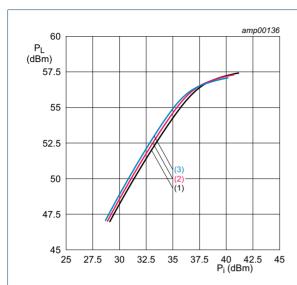
Fig 3. Power gain and drain efficiency as function of output power; typical values



 $V_{DS}$  = 50 V;  $I_{Dq}$  = 90 mA.

- (1) f = 902 MHz
- (2) f = 915 MHz
- (3) f = 928 MHz

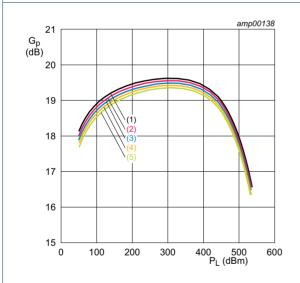
Fig 4. Power gain and drain efficiency as function of output power; typical values



 $V_{DS} = 50 \text{ V}; I_{Dq} = 90 \text{ mA}.$ 

- (1) f = 902 MHz
- (2) f = 915 MHz
- (3) f = 928 MHz

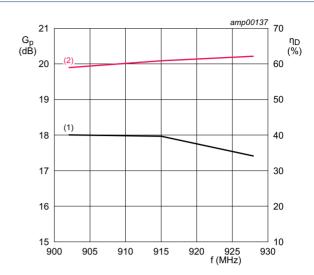
Fig 5. Output power as a function of input power; typical values



 $V_{DS} = 50 \text{ V}; f = 915 \text{ MHz}.$ 

- (1)  $I_{Dq} = 90 \text{ mA}$
- (2)  $I_{Dq} = 80 \text{ mA}$
- (3)  $I_{Dq} = 70 \text{ mA}$
- (4)  $I_{Dq} = 60 \text{ mA}$
- (5)  $I_{Dq} = 50 \text{ mA}$

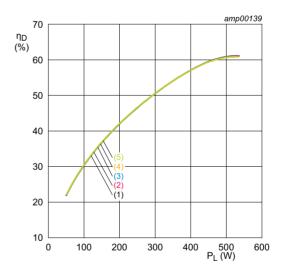
Fig 7. Power gain as a function of output power; typical values



 $V_{DS}$  = 50 V;  $I_{Dq}$  = 90 mA;  $P_L$  = 500 W.

- (1) G<sub>p</sub>
- (2) η<sub>D</sub>

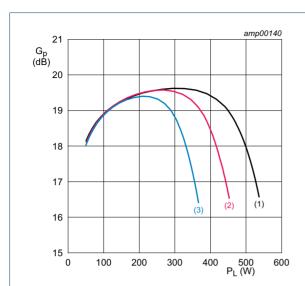
Fig 6. Power gain and drain efficiency as a function of frequency; typical values



 $V_{DS} = 50 \text{ V}; f = 915 \text{ MHz}.$ 

- (1)  $I_{Dq} = 90 \text{ mA}$
- (2)  $I_{Dq} = 80 \text{ mA}$
- (3)  $I_{Dq} = 70 \text{ mA}$
- (4)  $I_{Dq} = 60 \text{ mA}$
- (5)  $I_{Dq} = 50 \text{ mA}$

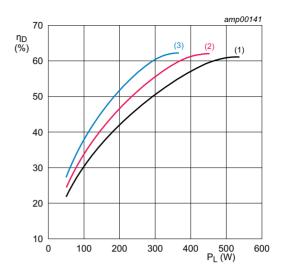
Fig 8. Drain efficiency as a function of output power; typical values



 $I_{Dq} = 90 \text{ mA}$ ; f = 915 MHz.

- (1)  $V_{DS} = 50 \text{ V}$
- (2)  $V_{DS} = 45 \text{ V}$
- (3)  $V_{DS} = 40 \text{ V}$

Fig 9. Power gain as a function of output power; typical values

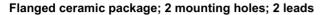


 $I_{Dq} = 90 \text{ mA}$ ; f = 915 MHz.

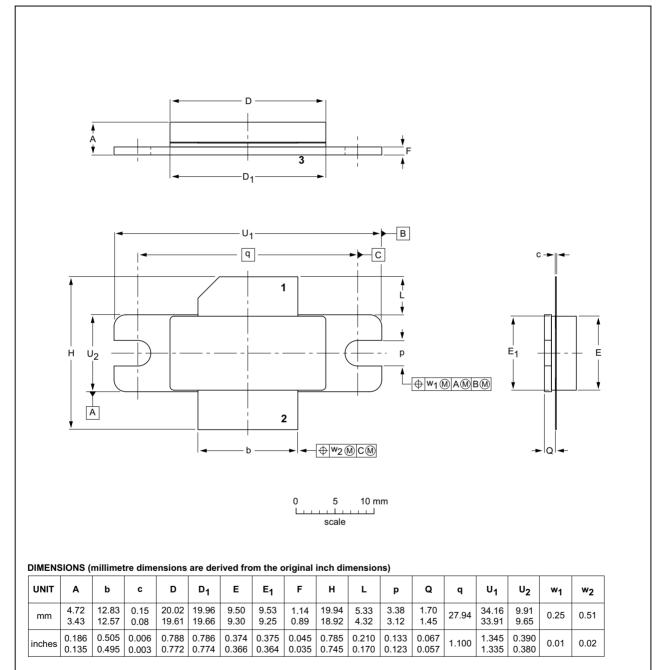
- (1)  $V_{DS} = 50 \text{ V}$
- (2)  $V_{DS} = 45 \text{ V}$
- (3)  $V_{DS} = 40 \text{ V}$

Fig 10. Drain efficiency as a function of output power; typical values

### 8. Package outline



SOT502A



OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE
SOT502A					<del>-03-01-10 -</del> 12-05-02

Fig 11. Package outline SOT502A

#### Earless flanged ceramic package; 2 leads

#### SOT502B

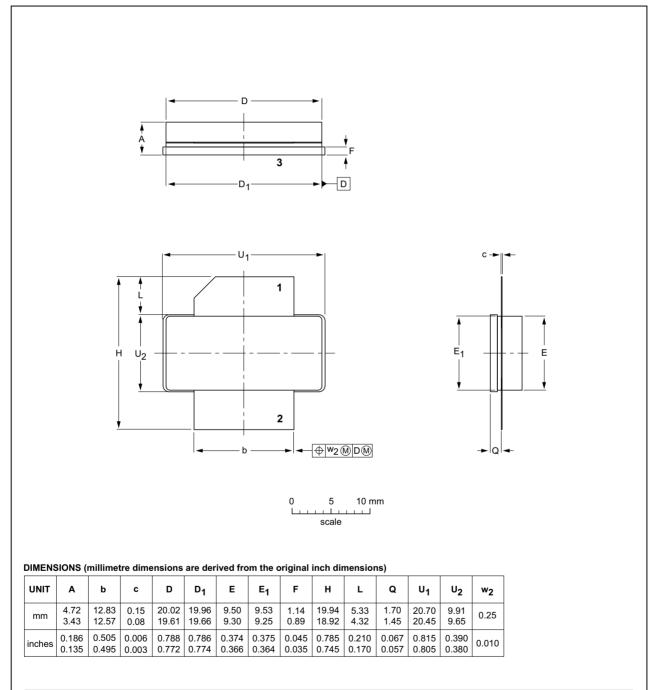


Fig 12. Package outline SOT502B

IEC

JEITA

**ISSUE DATE** 

07-05-09

12-05-02

EUROPEAN

**PROJECTION** 

REFERENCES

**JEDEC** 

OUTLINE

VERSION

SOT502B

### 9. Handling information

#### **CAUTION**



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the ANSI/ESD S20.20, IEC/ST 61340-5, JESD625-A or equivalent standards.

Table 10. ESD sensitivity

ESD model	Class
Charged Device Model (CDM); According to ANSI/ESDA/JEDEC standard JS-002	C1 [1]
Human Body Model (HBM); According to ANSI/ESDA/JEDEC standard JS-001	2 [2]

- [1] CDM classification C1 is granted to any part that passes after exposure to an ESD pulse of 250 V, but fails after exposure to an ESD pulse of 500 V.
- [2] HBM classification 2 is granted to any part that passes after exposure to an ESD pulse of 2000 V, but fails after exposure to an ESD pulse of 4000 V.

### 10. Abbreviations

Table 11. Abbreviations

Acronym	Description
CW	Continuous wave
ESD	ElectroStatic Discharge
ISM	Industrial, Scientific and Medical
LDMOS	Laterally Diffused Metal-Oxide Semiconductor
MTF	Median Time to Failure
SMD	Surface Mounted Device
VSWR	Voltage Standing-Wave Ratio

### 11. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BLF0910H6L500_H6LS500 v.2	20170413	Product data sheet	-	BLF0910H6L500_H6LS500 v.1
Modifications:	<u>Table 8 on page 3</u> : corrected GHz to MHz			
BLF0910H6L500_H6LS500 v.1	20161202	Product data sheet	-	-

### 12. Legal information

#### 12.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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BLF0910H6L500 H6LS500

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# BLF0910H6L500; BLF0910H6LS500

**Power LDMOS transistor** 

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# **AMPLEON**

# BLF0910H6L500; BLF0910H6LS500

**Power LDMOS transistor** 

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